



*The Institute for
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Design Guide for Microwave Circuit Boards Utilizing Soft Substrates

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Table of Contents

1.0 General	1	5.3.2.8 Immersion Tin	10
1.1 Purpose	1	5.3.2.9 Electroplated Tin	10
1.2 Scope	1	5.3.3 Galvanic Corrosion	10
1.3 Terms and Definitions	1	5.3.4 Chromate Conversion Coating	10
1.4 Interpretation	3	5.4 Conformal Coating	10
2.0 Applicable/Reference Documents	3	5.4.1 General Caution	10
2.1 IPC	3	6.0 Electrical Characteristics	10
2.2 ANSI	3 2	6.1 Stripline	11
2.3 Military Standards & Specifications	3 3	6.1.1 Narrow traces	11
2.5 Reference Information	3	6.1.2 Wide traces	11
3.0 Design Considerations	3	6.1.3 Asymmetric Stripline	11
3.1 Initial Input	3	6.2 Microstrip	11
3.2 Design Options	3	7.0 Detailed Board Requirements	14
3.3 Line Type, Materials, and Components	3	7.1 Machined Features	14
3.4 Electrical Design	3	7.1.1 Dimensioning and Tolerancing	14
3.5 Mechanical Design	5	7.1.2 Plated-Through Holes	15
3.6 Preliminary Design Review	5	7.1.2.1 Pinning/Ground Connections	15
3.7 Brassboard	5	7.1.3 Unplated Holes	16
3.8 Prototype	5	7.1.4 Depth Pockets and Slots	16
3.9 Documentation	5	7.1.5 Inner-Layer Access Machining	16
3.10 Final Design Review	5	7.1.6 Periphery	16
4.0 Documentation Requirements	5	7.1.7 NC Tapes	16
4.1 Design Features Printed	5	7.1.8 Dimensional Inspection	17
4.2 Master Drawing	5	7.2 Imaging	17
4.3 Master Pattern	6	7.2.1 Artwork	17
5.0 Materials	6	7.2.2 Photoresist	17
5.1 Microwave Printed Circuit Board Materials	6	7.2.3 Annular Rings	17
5.1.1 Substrate Selection	6	7.3 PTFE Activation	18
5.1.1.1 Relative Permittivity	6	7.4 Metallization	18
5.1.1.2 Loss Tangent	6	7.4.1 Plated Edge Designs	18
5.1.1.3 Thickness	6	7.4.2 Copper Plating	18
5.1.1.4 Environment	7	7.5 Etching	18
5.1.1.5 Cost	7	7.6 Bonding	19
5.1.1.6 Supplier	8	7.7 Testing	19
5.2 Bonding Films	8	8.0 Device Attachments and Packaging	19
5.2.1 Thermoplastic Bonding Films	8	8.1.1 Mechanical Mounting	19
5.2.2 Thermoset Bonding Films	8	8.1.2 Epoxies (both conductive and non conductive)	19
5.2.3 Bonding Considerations	8	8.1.3 Thermoplastic Films	20
5.3 Metals	8	8.1.4 Soldering	20
5.3.1 Cladding	8	8.1.5 Direct Bonding	20
5.3.1.1 Thin Cladding Considerations	8	8.2 Connector Attachment	20
5.3.1.2 Heavy Cladding Considerations	9	8.3 Device Attachment	21
5.3.2 Metal Plating	9	8.3.1 Welded Bonds	22
5.3.2.1 Electroless Copper	9	8.3.1.1 Resistance Welding	22
5.3.2.2 Electrodeposited Copper	9	8.3.1.2 Parallel Gap Welding	22
5.3.2.3 Nickel	9	8.3.1.3 Percussive Arc Welding	22
5.3.2.4 Gold	9	8.3.1.4 Laser Welding	22
5.3.2.5 Silver	9	8.3.1.5 Soldering	22
5.3.2.6 Tin-lead	9	8.3.2 Diffusion Bonding	22
5.3.2.7 Solder Coating	9		

8.3.2.1	Ultrasonic Welding	22
8.3.2.2	Thermal Compression Bonding	22
8.3.2.3	Thermosonic Bonding	22
8.3.3	Device Attachment	23
8.3.3.1	Ultrasonic Wire Bonding	23
8.3.3.2	Thermosonic (Ball) Bonding	23
8.3.3.3	Parallel Gap Welding	23
8.3.3.4	Thermal Compression Bonding	23
8.3.3.5	Solder Reflow	23
9.0	Quality Assurance	23
9.1	Quality Conformance Evaluations	24
9.2	Reliability	25

Figures

Figure 1	Microwave Circuit Design Flowchart	4
Figure 6.1-1	Stripline	12
Figure 6.1-2	Cutaway View of Stripline	12
Figure 6.2-1	Cross-sectional view of microstrip line without metal cover	12
Figure 6.2-2	Cross-sectional view of microstrip line with metal cover	13
Figure 7-1	Comparison of Bilateral and True Position Tolerancing Methods	15
Figure 7-2	Straight Headless Pin (Solid)	16
Figure 7-3	Straight Headed Pin (Solid)	16
Figure 7-4	Roll Pin	16
Figure 8-1	Mounting a Surface Connector to a Buried Land	21
Figure 8-2	Alternative Mounting Method	22
Figure 9-1	Coupon Placement Recommendations	24
Figure 9-2	Test Coupons A and B	25
Figure 9-3	Test Coupon C, External Layers Only	25
Figure 9-4	Coupon E (Dielectric Withstanding Voltage, Moisture Assistance and Insulation Assistance) ..	26
Figure 9-5	Coupon F (Registration)	26

Tables

Table 1	Typical Microwave Materials	6
Table 2	Typical Characteristics of Thermoplastic Bonding Films	8
Table 3	Characteristics of Thermoset Bonding Films	8
Table 4	Most Common Thin Copper Foils	9
Table 5	Thick metal Claddings	9
Table 6	Coupon Frequency Requirements	24

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1.0 General

1.1 Purpose The purpose of this document is to aid in the design of microwave circuit boards. This document is not intended to include information relating to the detailed electrical design of microwave circuits. Rather, it is intended to include information from which practical, functional, and cost-effective circuit boards may be designed once the design engineer has determined the circuit requirements. This design aid is to be used by microwave circuit design engineers, packaging engineers, and drafters. It is restricted to microwave circuit boards using substrates specified in IPC-L-125 (See section 5.0).

1.2 Scope This document addresses microwave circuitry. For the purpose of this document microwaves apply to radio waves in the frequency range of 100 MHz and to 30 GHz. The document also applies to operations in the region where distributed constant circuits enclosed by conducting boundaries are used instead of conventional lumped-constant circuit elements.

1.3 Terms and Definitions

Anisotropy: The condition for a substance having differing values for properties, such as permittivity, depending on the direction within the material. Isotropy describes the case where a property is the same in all directions. Isotropy may exist in non-crystalline homogeneous (single phase) substances. In a microwave laminate based on a polymer composite, anisotropy of the dielectric layer exists.

Characteristic impedance (Z_0): For a uniform transmission line of any length, the ratio of inductance per unit length to capacitance per unit length. A 50 ohm characteristic impedance is often used because it matches that of most test instrumentation. When a signal propagating along a transmission line encounters a change in Z_0 , scattering of the signal will occur, that is, some of the signal will be reflected backwards along the line.

Coaxial Cable (coax): A transmission line having a center conductor coaxial with an outside shield conductor of inside diameter larger than the center conductor and separated from it by dielectric.

Coefficient of Thermal Expansion (CTE): The ratio of dimensional change of a material to the dimension per degree of temperature change. Typically CTE values refer to linear dimensions in a particular direction such as the X, Y, Z

orthogonal axes where Z refers to the thickness direction and X to the planar direction of greatest orientation of a composite structure.

Copper Weight: The mass of copper per unit area for a foil. The copper foil industry typically expresses weight in ounces per square foot (oz/ft^2). A copper foil weight of $1 \text{ oz}/\text{ft}^2$ corresponds to a nominal $34 \mu\text{m}$ thickness.

Copper Thickness: The thickness dimension of the copper cladding on a laminate.

Cut-off Frequency: Frequency of a transmission line at which modes other than TEM are generated. Also, in a low-pass or highpass filter it is the frequency where the response falls off by 3 dB.

Dielectric: An electrically insulating or non-conducting material. The properties of permittivity (dielectric constant) and loss tangent (loss factor or $\tan \delta$) for such a material determine how it will alter an electromagnetic wave as it propagates through the material.

Dielectric Thickness: Dimension of the laminate excluding the thickness of the copper cladding.

Directional coupler: A device or structure which causes some of the energy propagating along one transmission line to be transferred to a second transmission line so that most of the transferred energy propagates in a specific direction along the second line. The other direction is considered isolated. At lower frequencies this function can be accomplished in a design with lumped capacitive and inductive elements while at microwave frequencies two stripline or microstrip traces that run parallel to each other for a certain distance can serve the purpose. One use for such devices is to sample amplitude or phase of a signal traveling in a specific direction.

Directivity: The difference between the isolation and the coupling values of a directional coupler.

Dissipation Factor: Also referred to as $\tan \delta$, the ratio of the energy dissipated in a material to the energy stored.

Distributed Component: A component whose parameters are distributed over an area of copper on a microwave laminate.

Effective Permittivity (effective dielectric constant or K'_{eff}): The permittivity of a single dielectric medium, such as in coaxial line or stripline, that has the equivalent propagation velocity of a mixed media configuration, such as air and solid dielectric in microstrip.